



Product Range

thermal processing

IR Vacuum Reflow

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Table Top System
450°C/700°C



450°C/750°C
1100°C



Process Furnace

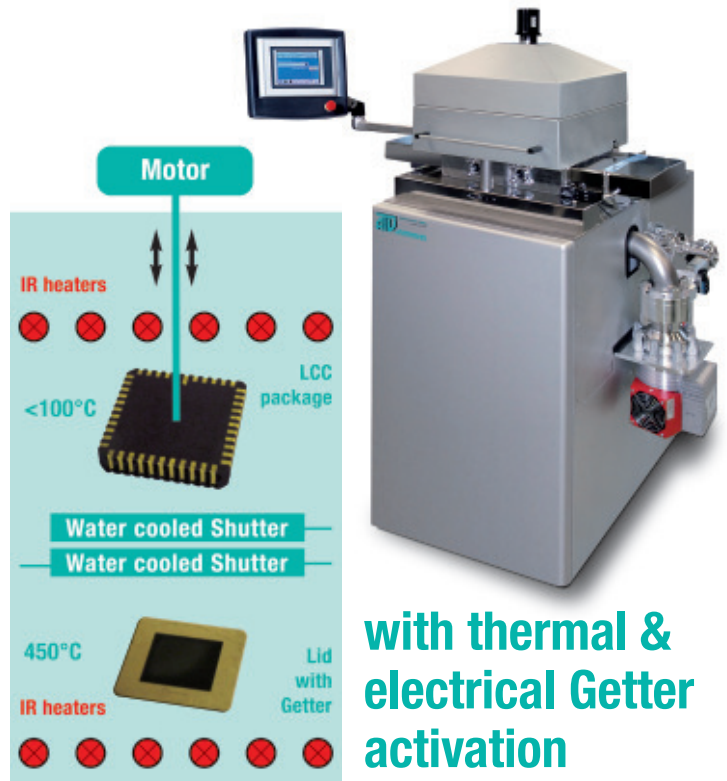
Multipurpose Fast Ramping Process Furnace green energy over 420 worldwide units

- no energy/gas consumption during stand by loading at room temperature – ramp up – processing – controlled active cool down
- LPCVD: Poly Si, Si₃N₄, epitaxy, LTO, TEOS, MOCVD, CNT, annealing, LTCC sintering, Polyimide, alloying, thick film paste, diffusion, thermal oxide/VECSEL
- max. 1100°C, ultimate vacuum ~ 7 x 10⁻⁷ mbar
- up to 100 wafers

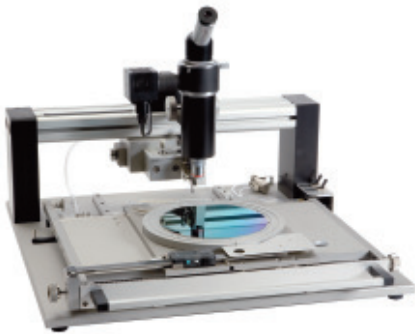
IR Vacuum Reflow/Brazing/RTA over 430 worldwide units

- up to 50K/s, 450°C, max. 1100°C, ultimate pressure ~ 7 x 10⁻⁷ mbar
- 3 bar absolute, > 3 bar in inner reactor, plasma, formic acid, H₂, CO, flux management
- MEMS cap/package sealing, IGBT/DBC, laser bar, alloying, backing wafer bump/solder ball reflow, flip chip, cassette to cassette, In Line

MEMS cap/package lid sealing



with thermal & electrical Getter activation

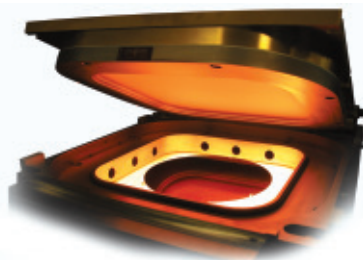


Diamond Scribers

up to 200 mm Ø

Customized IR LPCVD/RTP

- IR lamp array based
- with temperature/pressure modulation capability
- with easy to replace quartz in liner
- with in situ rapid annealing up to 1050°C



PHP 603-LTCC Sintering Press

press force:
max. 50 kN,
min. 500 N,

max.
substrate size:
8" x 8",
12" x 12"
on request

max.
temperature:
1100°C

